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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-8FX
Core Size	8-Bit
Speed	16MHz
Connectivity	I²C, LINbus, SIO, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	41
Program Memory Size	60KB (60K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.88V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb95f698kpmc2-g-sne2

3. Differences Among Products And Notes On Product Selection

- Current consumption
  When using the on-chip debug function, take account of the current consumption of Flash memory program/erase.
  For details of current consumption, see “Electrical Characteristics”.

- Package
  For details of information on each package, see “Packages And Corresponding Products” and “Package Dimension”.

- Operating voltage
  The operating voltage varies, depending on whether the on-chip debug function is used or not.
  For details of operating voltage, see “Electrical Characteristics”.

- On-chip debug function
  The on-chip debug function requires that V_{CC}, V_{SS} and one serial wire be connected to an evaluation tool. For details of the connection method, refer to “CHAPTER 25 EXAMPLE OF SERIAL PROGRAMMING CONNECTION” in “New 8FX MB95690K Series Hardware Manual”.

Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

- **Latch-up**

  Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

  CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

  (1) Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.

  (2) Be sure that abnormal current flows do not occur during the power-on sequence.

- **Observance of Safety Regulations and Standards**

  Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

- **Fail-Safe Design**

  Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

- **Precautions Related to Usage of Devices**

  Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

  CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

8.2 Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mount type. In either case, for heat resistance during soldering, you should only mount under Cypress's recommended conditions. For detailed information about mount conditions, contact your sales representative.

- **Lead Insertion Type**

  Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.

  Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions.

  If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

- **Surface Mount Type**

  Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges.

  You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

- **Lead-Free Packaging**

  CAUTION: When ball grid array (BGA) packages with Sn-Ag-Cu balls are mounted using Sn-Pb eutectic soldering, junction strength may be reduced under some conditions of use.

- **Storage of Semiconductor Devices**

  Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

  (1) Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.

  (2) Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between 5°C and 30°C.
  When you open Dry Package that recommends humidity 40% to 70% relative humidity.

  (3) When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.

  (4) Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

- **Baking**

  Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

  Condition: 125°C/24 h

- **Static Electricity**

  Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

  (1) Maintain relative humidity in the working environment between 40% and 70%.
  Use of an apparatus for ion generation may be needed to remove electricity.

  (2) Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.

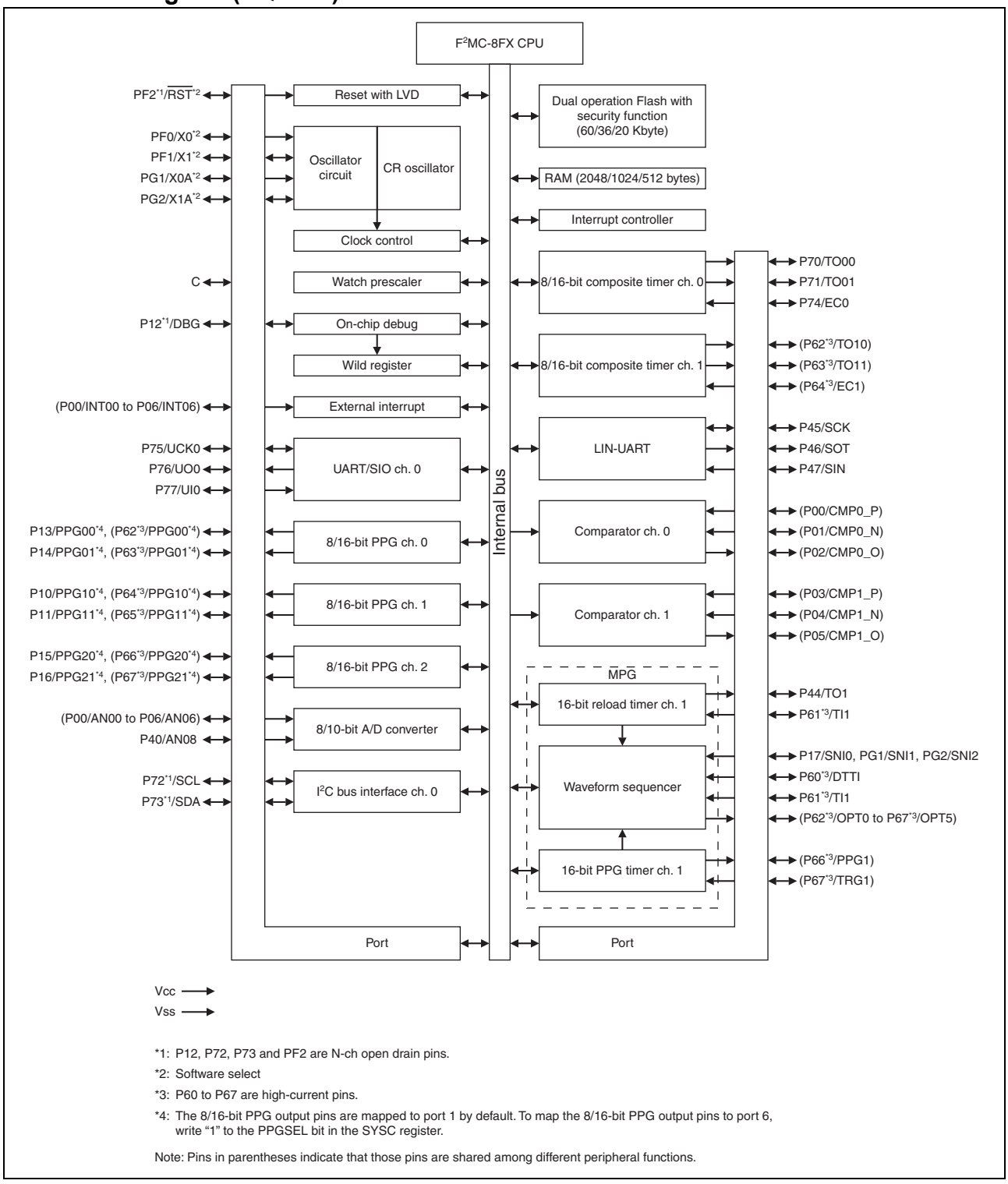
  (3) Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 MΩ).
  Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.

  (4) Ground all fixtures and instruments, or protect with anti-static measures.

  (5) Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

- Note on serial communication
  In serial communication, reception of wrong data may occur due to noise or other causes. Therefore, design a printed circuit board to prevent noise from occurring. Taking account of the reception of wrong data, take measures such as adding a checksum to the end of data in order to detect errors. If an error is detected, retransmit the data.

11. Block Diagram (LQF044)



*1: P12, P72, P73 and PF2 are N-ch open drain pins.

*2: Software select

*3: P60 to P67 are high-current pins.

*4: The 8/16-bit PPG output pins are mapped to port 1 by default. To map the 8/16-bit PPG output pins to port 6, write "1" to the PPGSEL bit in the SYSC register.

Note: Pins in parentheses indicate that those pins are shared among different peripheral functions.

14. Memory Space

The memory space of the MB95690K Series is 64 Kbyte in size, and consists of an I/O area, an extended I/O area, a data area, and a program area. The memory space includes areas for specific applications such as general-purpose registers and a vector table.

14.1 I/O area (addresses: 0x0000 to 0x007F)

- This area contains the control registers and data registers for built-in peripheral functions.
- As the I/O area forms part of the memory space, it can be accessed in the same way as the memory. It can also be accessed at high-speed by using direct addressing instructions.

14.2 Extended I/O area (addresses: 0x0F80 to 0x0FFF)

- This area contains the control registers and data registers for built-in peripheral functions.
- As the extended I/O area forms part of the memory space, it can be accessed in the same way as the memory.

14.3 Data area

- Static RAM is incorporated in the data area as the internal data area.
- The internal RAM size varies according to product.
- The RAM area from 0x0090 to 0x00FF can be accessed at high-speed by using direct addressing instructions.
- In MB95F698K, the area from 0x0090 to 0x047F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
- In MB95F696K, the area from 0x0090 to 0x047F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
- In MB95F694K, the area from 0x0090 to 0x028F is an extended direct addressing area. It can be accessed at high-speed by direct addressing instructions with a direct bank pointer set.
- In MB95F694K/F696K/F698K, the area from 0x0100 to 0x01FF can be used as a general-purpose register area.

14.4 Program area

- The Flash memory is incorporated in the program area as the internal program area.
- The Flash memory size varies according to product.
- The area from 0xFFC0 to 0xFFFF is used as the vector table.
- The area from 0xFFBB to 0xFFBF is used to store data of the non-volatile register.

17. I/O Ports

- List of port registers

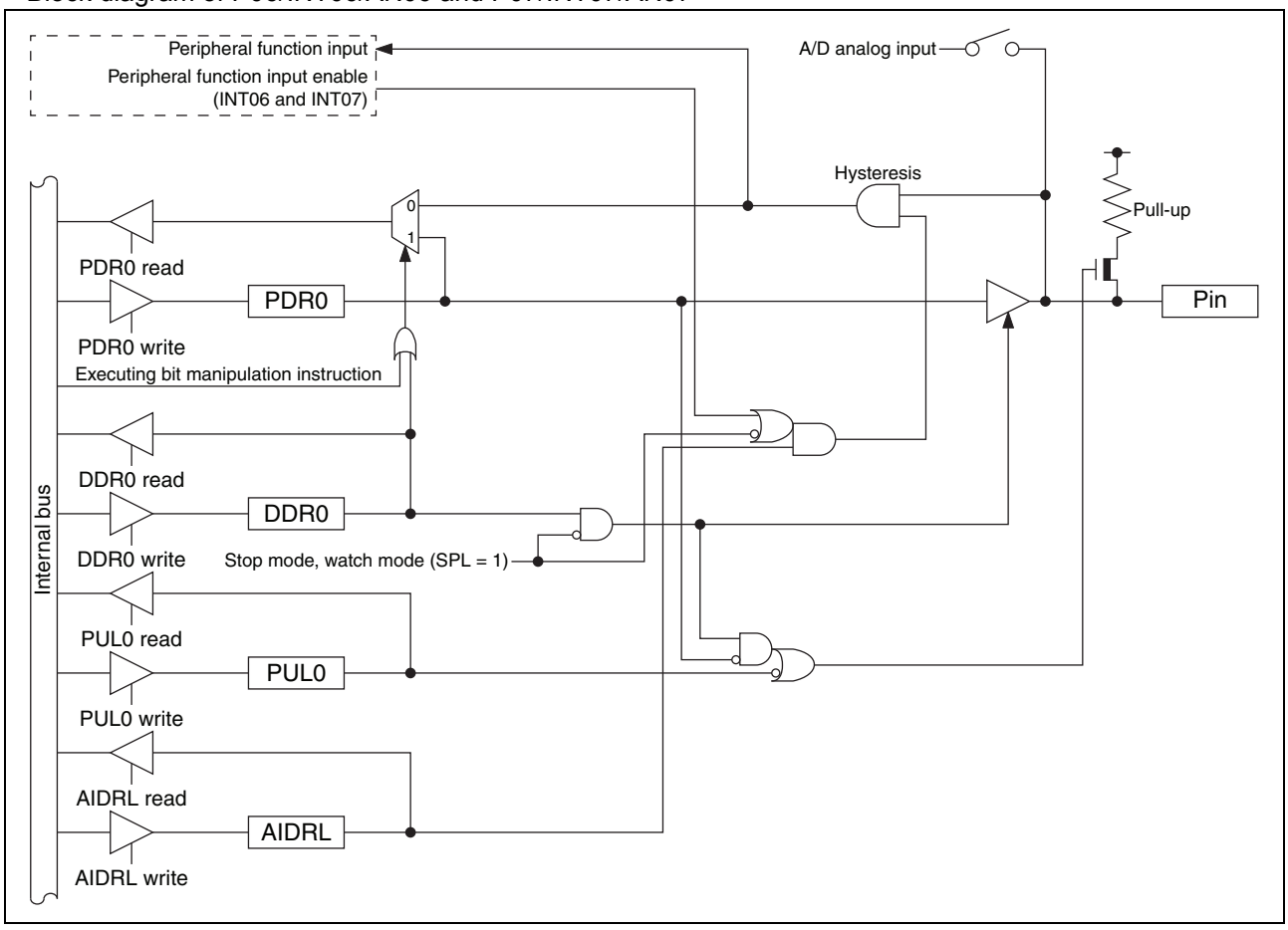
Register name		Read/Write	Initial value
Port 0 data register	PDR0	R, RM/W	0b00000000
Port 0 direction register	DDR0	R/W	0b00000000
Port 1 data register	PDR1	R, RM/W	0b00000000
Port 1 direction register	DDR1	R/W	0b00000000
Port 4 data register	PDR4	R, RM/W	0b00000000
Port 4 direction register	DDR4	R/W	0b00000000
Port 6 data register	PDR6	R, RM/W	0b00000000
Port 6 direction register	DDR6	R/W	0b00000000
Port 7 data register	PDR7	R, RM/W	0b00000000
Port 7 direction register	DDR7	R/W	0b00000000
Port F data register	PDRF	R, RM/W	0b00000000
Port F direction register	DDRF	R/W	0b00000000
Port G data register	PDRG	R, RM/W	0b00000000
Port G direction register	DDRG	R/W	0b00000000
Port 0 pull-up register	PUL0	R/W	0b00000000
Port 1 pull-up register	PUL1	R/W	0b00000000
Port 4 pull-up register	PUL4	R/W	0b00000000
Port 6 pull-up register	PUL6	R/W	0b00000000
Port 7 pull-up register	PUL7	R/W	0b00000000
Port G pull-up register	PULG	R/W	0b00000000
A/D input disable register (upper)	AIDRH	R/W	0b00000000
A/D input disable register (lower)	AIDRL	R/W	0b00000000

R/W : Readable/writable (The read value is the same as the write value.)
R, RM/W : Readable/writable (The read value is different from the write value. The write value is read by the read-modify-write (RMW) type of instruction.)

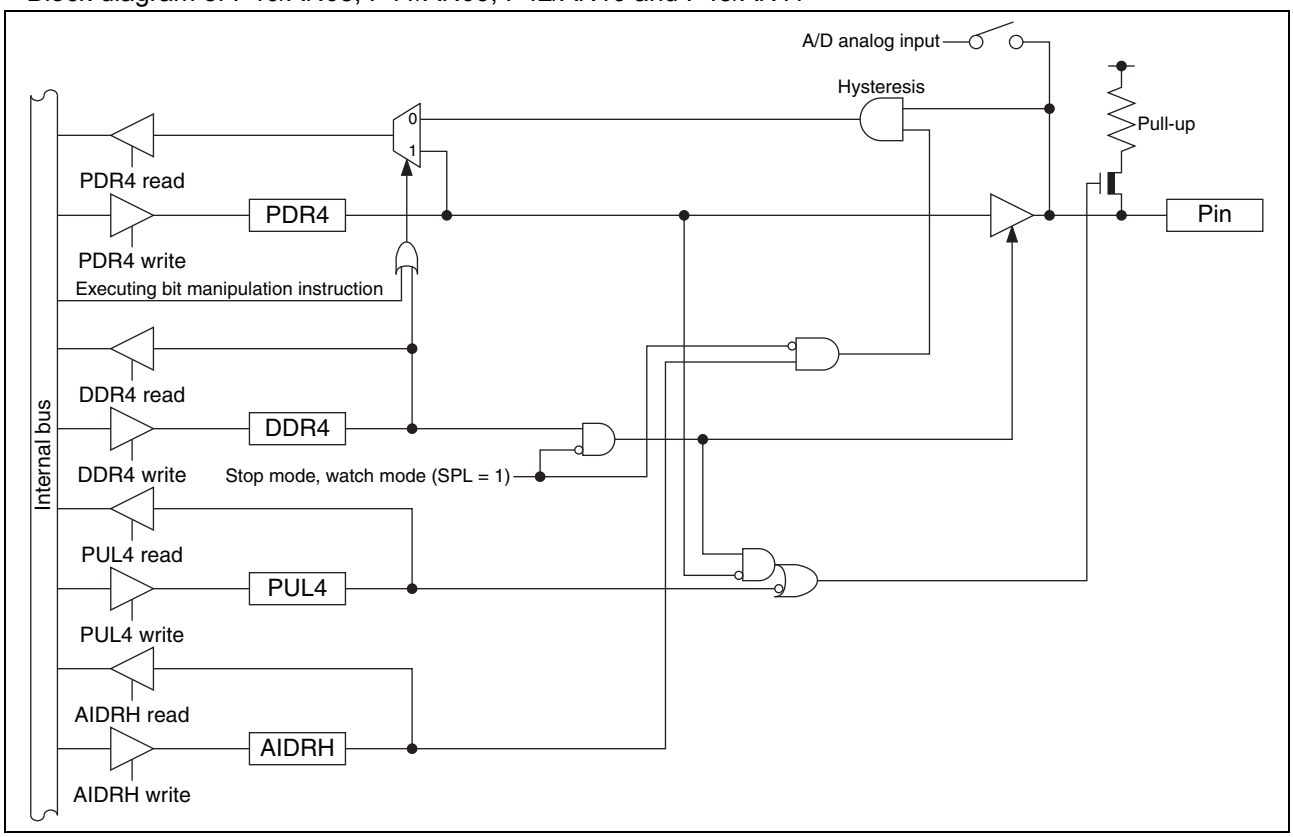
- P06/INT06/AN06 pin
  This pin has the following peripheral functions:
  - External interrupt input pin (INT06)
  - 8/10-bit A/D converter analog input pin (AN06)

- P07/INT07/AN07 pin
  This pin has the following peripheral functions:
  - External interrupt input pin (INT07)
  - 8/10-bit A/D converter analog input pin (AN07)

- Block diagram of P06/INT06/AN06 and P07/INT07/AN07



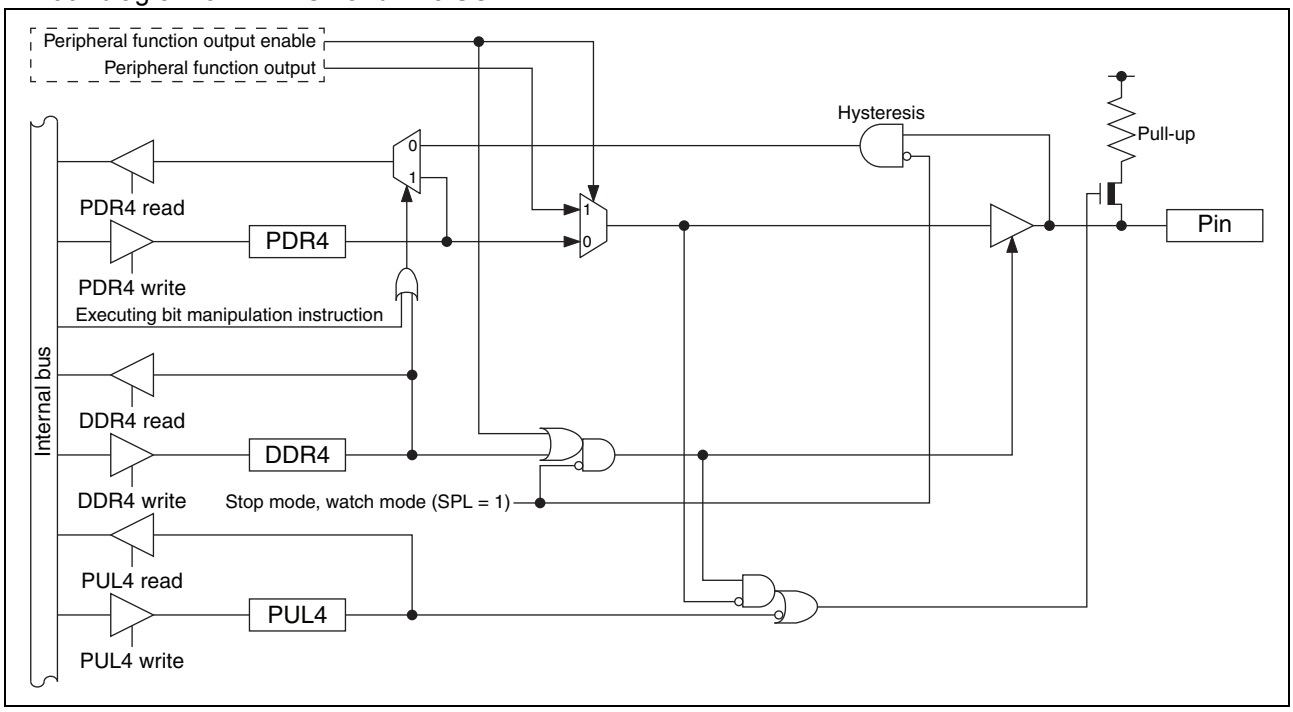
- Block diagram of P40/AN08, P41/AN09, P42/AN10 and P43/AN11



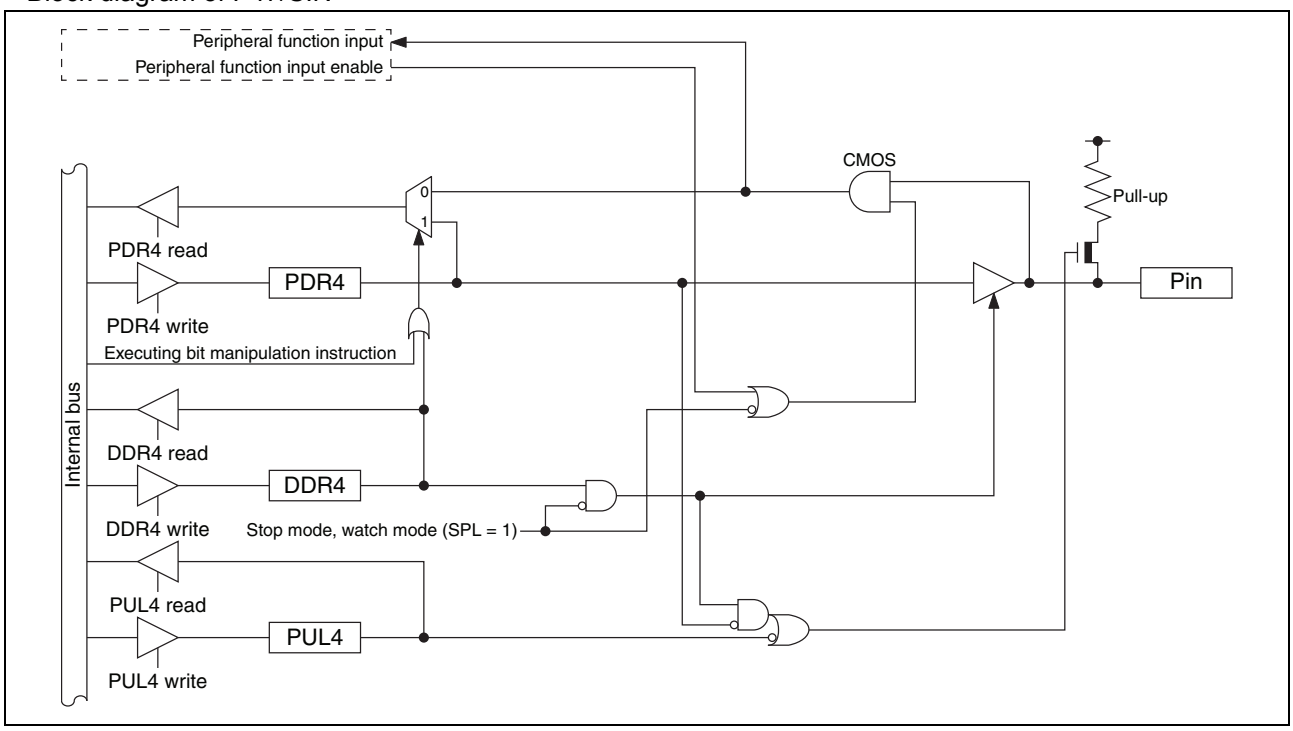
- P44/TO1 pin
  This pin has the following peripheral function:
  - 16-bit reload timer ch. 1 output pin (TO1)

- P46/SOT pin
  This pin has the following peripheral function:
  - LIN-UART data output pin (SOT)

- Block diagram of P44/TO1 and P46/SOT



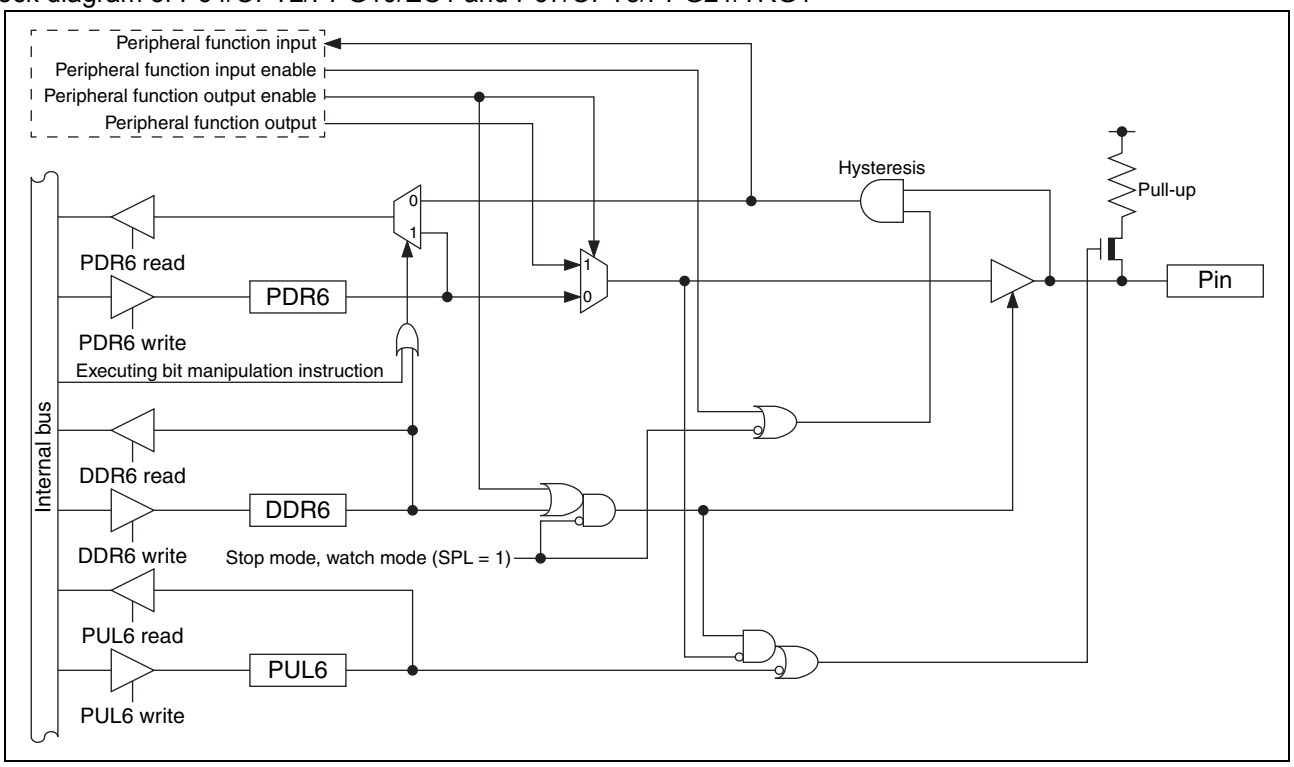
- Block diagram of P47/SIN



- P64/OPT2/PPG10/EC1 pin
  This pin has the following peripheral functions:
  - MPG waveform sequencer output pin (OPT2)
  - 8/16-bit PPG ch. 1 output pin (PPG10)
  - 8/16-bit composite timer ch. 1 clock input pin (EC1)

- P67/OPT5/PPG21/TRG1 pin
  This pin has the following peripheral functions:
  - MPG waveform sequencer output pin (OPT5)
  - 8/16-bit PPG ch. 2 output pin (PPG21)
  - 16-bit PPG timer ch. 1 trigger input pin (TRG1)

- Block diagram of P64/OPT2/PPG10/EC1 and P67/OPT5/PPG21/TRG1



17.5 Port 7

Port 7 is a general-purpose I/O port. This section focuses on its functions as a general-purpose I/O port. For details of peripheral functions, refer to their respective chapters in “New 8FX MB95690K Series Hardware Manual”.

17.5.1 Port 7 configuration

Port 7 is made up of the following elements.

- General-purpose I/O pins/peripheral function I/O pins
- Port 7 data register (PDR7)
- Port 7 direction register (DDR7)
- Port 7 pull-up register (PUL7)

17.5.2 Block diagrams of port 7

- P70/TO00 pin

  This pin has the following peripheral function:
  - 8/16-bit composite time ch. 0 output pin (TO00)

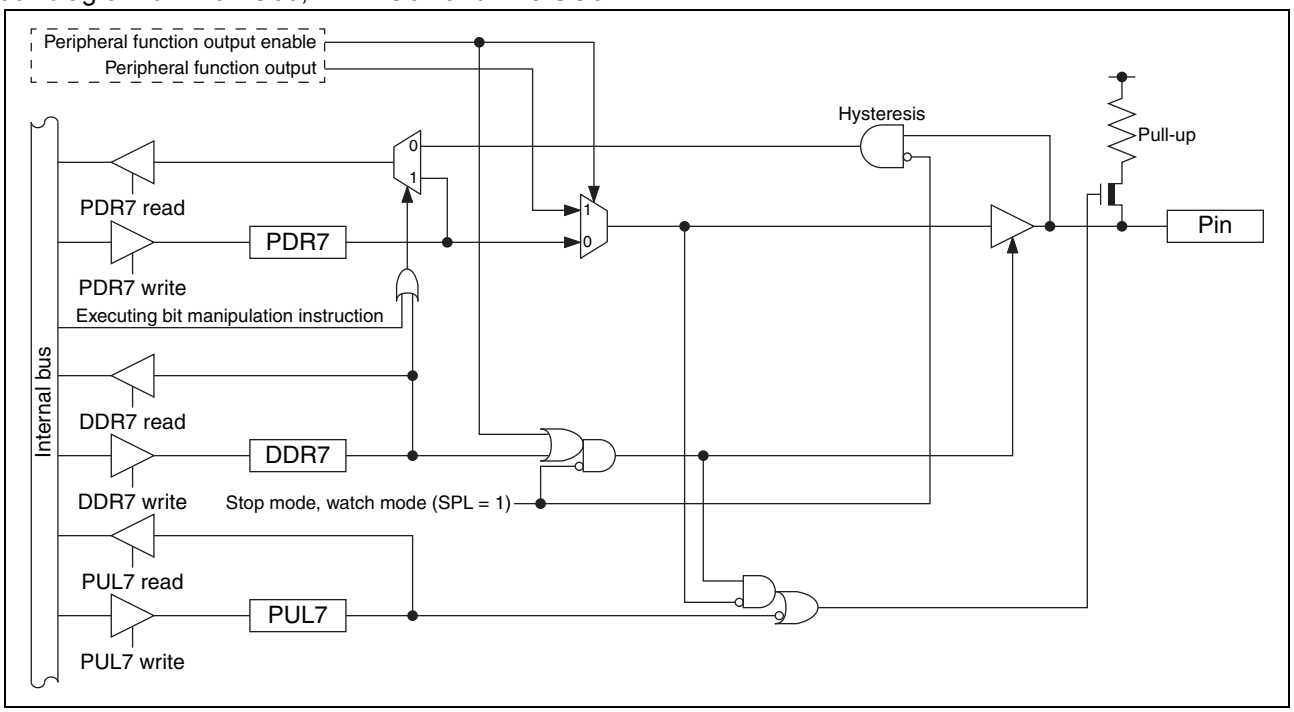
- P71/TO01 pin

  This pin has the following peripheral function:
  - 8/16-bit composite timer ch. 0 output pin (TO01)

- P76/UO0 pin

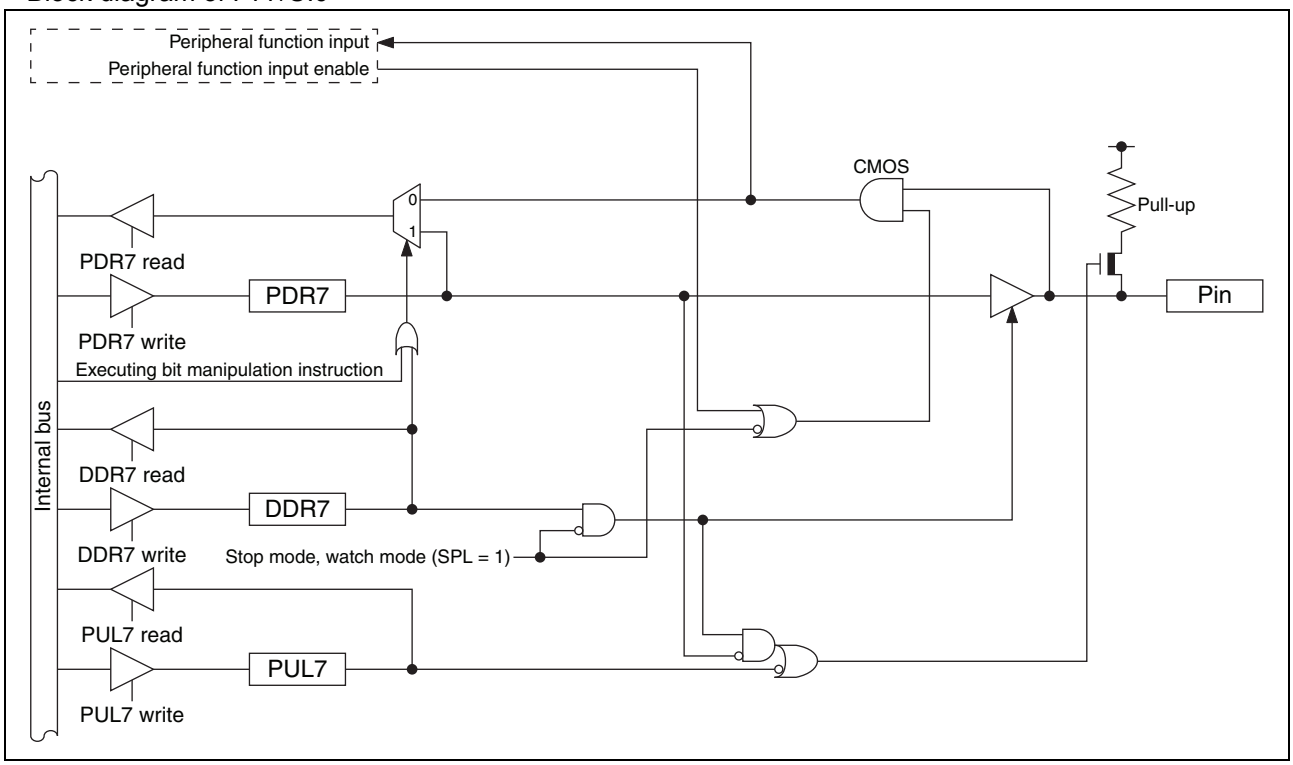
  This pin has the following peripheral function:
  - UART/SIO ch. 0 data output pin (UO0)

- Block diagram of P70/TO00, P71/TO01 and P76/UO0



- P77/UI0 pin
  This pin has the following peripheral function:
  - UART/SIO ch. 0 data input pin (UI0)

- Block diagram of P77/UI0



17.6.4 Port F operations

- Operation as an output port
  - A pin becomes an output port if the bit in the DDRF register corresponding to that pin is set to “1”.
  - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
  - When a pin is used as an output port, it outputs the value of the PDRF register to external pins.
  - If data is written to the PDRF register, the value is stored in the output latch and is output to the pin set as an output port as it is.
  - Reading the PDRF register returns the PDRF register value.

- Operation as an input port
  - A pin becomes an input port if the bit in the DDRF register corresponding to that pin is set to “0”.
  - For a pin shared with other peripheral functions, disable the output of such peripheral functions.
  - If data is written to the PDRF register, the value is stored in the output latch but is not output to the pin set as an input port.
  - Reading the PDRF register returns the pin value. However, if the read-modify-write (RMW) type of instruction is used to read the PDRF register, the PDRF register value is returned.

- Operation at reset
  If the CPU is reset, all bits in the DDRF register are initialized to “0” and port input is enabled.

- Operation in stop mode and watch mode
  - If the pin state setting bit in the standby control register (STBC:SPL) is set to “1” and the device transits to stop mode or watch mode, the pin is compulsorily made to enter the high impedance state regardless of the DDRF register value. The input of that pin is locked to “L” level and blocked in order to prevent leaks due to input open.
  - If the pin state setting bit is “0”, the state of the port I/O or that of the peripheral function I/O remains unchanged and the output level is maintained.

17.7.3 Port G registers

- Port G register functions

Register abbreviation	Data	Read	Read by read-modify-write (RMW) instruction	Write
PDRG	0	Pin state is “L” level.	PDRG value is “0”.	As output port, outputs “L” level.
	1	Pin state is “H” level.	PDRG value is “1”.	As output port, outputs “H” level.
DDRG	0	Port input enabled		
	1	Port output enabled		
PULG	0	Pull-up disabled		
	1	Pull-up enabled		

- Correspondence between registers and pins for port G

	Correspondence between related register bits and pins							
Pin name	**-**	**-**	**-**	**-**	**-**	**PG2**	**PG1**	**-**
PDRG	-	-	-	-	-	bit2	bit1	-
DDRG								
PULG								

(Continued)

Pin name	Normal operation	Sleep mode	Stop mode		Watch mode		On reset
			SPL=0	SPL=1	SPL=0	SPL=1	
P72/SCL P73/SDA	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2, *9	- Hi-Z - Input blocked*2, *9	- Previous state kept - Input blocked*2, *9	- Hi-Z - Input blocked*2, *9	- Hi-Z - Input enabled*3 (However, it does not function.)
P70/TO00 P71/TO01 P76/UO0	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2	- Hi-Z*5 - Input blocked*2	- Previous state kept - Input blocked*2	- Hi-Z*5 - Input blocked*2	- Hi-Z - Input enabled*3 (However, it does not function.)
P74/EC0 P75/UCK0 P77/UI0	I/O port/ peripheral function I/O	I/O port/ peripheral function I/O	- Previous state kept - Input blocked*2, *7	- Hi-Z*5 - Input blocked*2, *7	- Previous state kept - Input blocked*2, *7	- Hi-Z*5 - Input blocked*2, *7	- Hi-Z - Input enabled*3 (However, it does not function.)

SPL: Pin state setting bit in the standby control register (STBC:SPL)
Hi-Z: High impedance
*1: The pin stays at the state shown when configured as a general-purpose I/O port.
*2: “Input blocked” means direct input gate operation from the pin is disabled.
*3: “Input enabled” means that the input function is enabled. While the input function is enabled, execute a pull-up or pull-down operation in order to prevent leaks due to external input. If a pin is used as an output port, its pin state is the same as that of other ports.
*4: The PF2/$\overline{\text{RST}}$ pin stays at the state shown when configured as a reset pin.
*5: The pull-up control setting is still effective.
*6: Though input is blocked, an external interrupt can be input when the external interrupt request is enabled, and an analog signal can also be input to generate a comparator interrupt when the comparator interrupt is enabled.
*7: Though input is blocked, an external interrupt can be input when the external interrupt request is enabled.
*8: The output function of the comparator is still in operation in stop mode and watch mode.
*9: The I^2C bus interface can wake up the MCU in stop mode or watch mode when its MCU standby mode wakeup function is enabled. For details of the MCU standby mode wakeup function, refer to “New 8FX MB95690K Series Hardware Manual”.

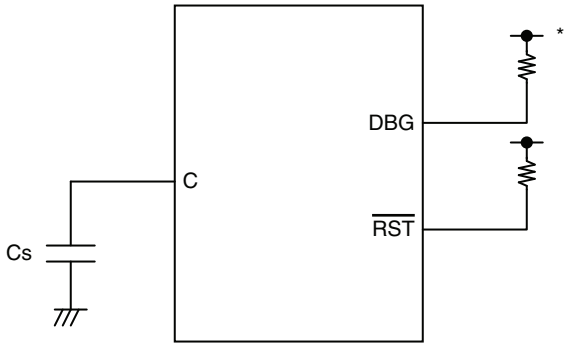
20.2 Recommended Operating Conditions

(V_{SS} = 0.0 V)

Parameter	Symbol	Value		Unit	Remarks
		Min	Max		
Power supply voltage	V_{CC}	2.88	5.5	V	
Decoupling capacitor	C_S	0.022	1	µF	*
Operating temperature	T_A	–40	+85	°C	Other than on-chip debug mode
		+5	+35		On-chip debug mode

*: Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the V_{CC} pin must have a capacitance equal to or larger than the capacitance of C_S. For the connection to a decoupling capacitor C_S, see the diagram below. To prevent the device from unintentionally entering an unknown mode due to noise, minimize the distance between the C pin and C_S and the distance between C_S and the V_{SS} pin when designing the layout of a printed circuit board.

- DBG / $\overline{\text{RST}}$ / C pins connection diagram



*: Connect the DBG pin to an external pull-up resistor of 2 kΩ or above. After power-on, ensure that the DBG pin does not stay at “L” level until the reset output is released. The DBG pin becomes a communication pin in debug mode. Since the actual pull-up resistance depends on the tool used and the interconnection length, refer to the tool document when selecting a pull-up resistor.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.

Any use of semiconductor devices will be under their recommended operating condition.
Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.

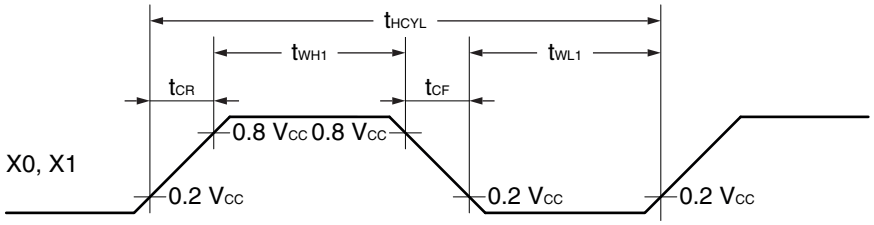
No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.

(V_{CC} = 2.88 V to 5.5 V, V_{SS} = 0.0 V, T_A = –40 °C to +85 °C)

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min	Typ	Max		
Clock cycle time	t_{HCYL}	X0, X1	—	61.5	—	1000	ns	When the main oscillation circuit is used
		X0	X1: open	83.4	—	1000	ns	When an external clock is used
		X0, X1	*	30.8	—	1000	ns	
	t_{LCYL}	X0A, X1A	—	—	30.5	—	µs	When the subclock is used
Input clock pulse width	t_{WH1}, t_{WL1}	X0	X1: open	33.4	—	—	ns	When an external clock is used, the duty ratio should range between 40% and 60%.
		X0, X1	*	12.4	—	—	ns	
	t_{WH2}, t_{WL2}	X0A	—	—	15.2	—	µs	
Input clock rising time and falling time	t_{CR}, t_{CF}	X0, X0A	X1: open	—	—	5	ns	When an external clock is used
		X0, X1, X0A, X1A	*	—	—	5	ns	
CR oscillation start time	t_{CRHWK}	—	—	—	—	50	µs	When the main CR clock is used
	t_{CRLWK}	—	—	—	—	30	µs	When the sub-CR clock is used
PLL oscillation start time	$t_{MCRPLLWK}$	—	—	—	—	100	µs	When the main CR PLL clock is used

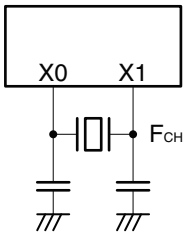
*: The external clock signal is input to X0 and the inverted external clock signal to X1.

- Input waveform generated when an external clock (main clock) is used

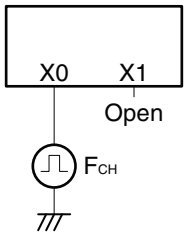


- Figure of main clock input port external connection

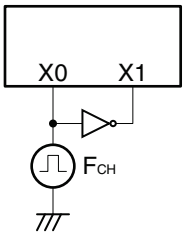
When a crystal oscillator or a ceramic oscillator is used



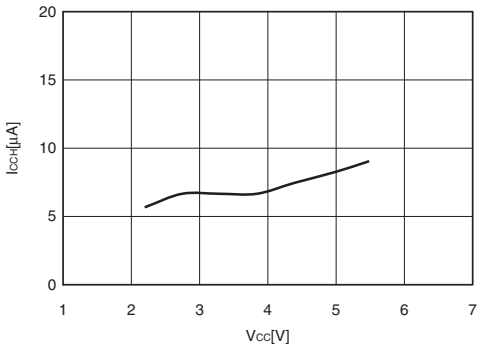
When an external clock is used (X1 is open)



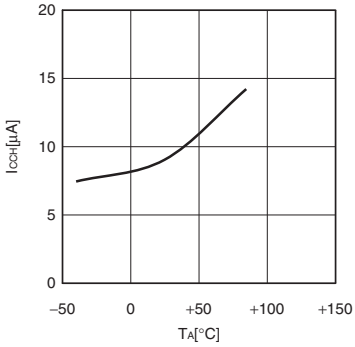
When an external clock is used



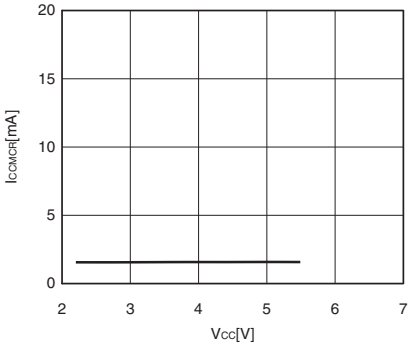
I_{CCH} – V_{CC}
T_A = +25 °C, F_{MPL} = (stop)
Substop mode with the external clock stopping



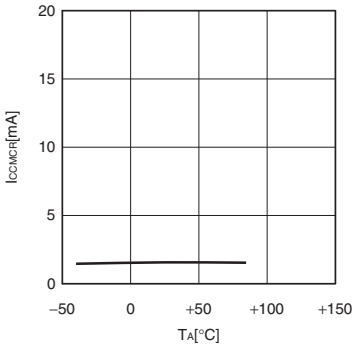
I_{CCH} – T_A
V_{CC} = 5.5 V, F_{MPL} = (stop)
Substop mode with the external clock stopping



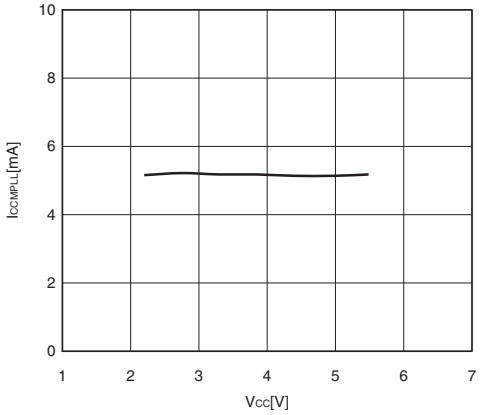
I_{CCMCR} – V_{CC}
T_A = +25 °C, F_{MP} = 4 MHz (no division)
Main CR clock mode



I_{CCMCR} – T_A
V_{CC} = 5.5 V, F_{MP} = 4 MHz (no division)
Main CR clock mode



I_{CCMPLL} – V_{CC}
T_A = +25 °C, F_{MP} = 16 MHz (PLL multiplication rate: 4)
Main CR PLL clock mode



I_{CCMPLL} – T_A
V_{CC} = 5.5 V, F_{MP} = 16 MHz (PLL multiplication rate: 4)
Main CR PLL clock mode